

STATUTORY DECLARATION

I, Takahiko NAKAZAWA, of Taiyo Seimei Otsuka Building  
3F, 2-25-1, Kitaotsuka, Toshimaku, Tokyo, 170-0004, Japan, do  
solemnly and sincerely declare as follows:

I am well acquainted with the English and Japanese  
languages.

The attached translation is true into the English  
language of the accompanying certified copy of the document  
filed in the name of Fuji Photo Film Co., Ltd., in the Japanese  
Patent Office on 11 September 2003, in respect to an application  
for Patent.

This 24th day of June 2009,

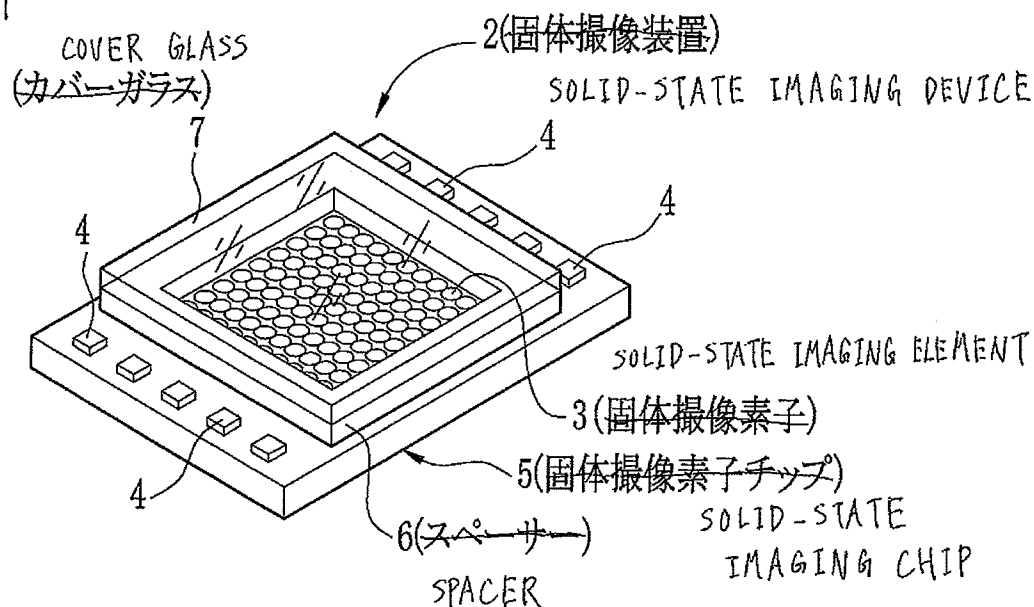
Takahiko Nakazawa

Takahiko NAKAZAWA

【書類名】図面 DRAWINGS

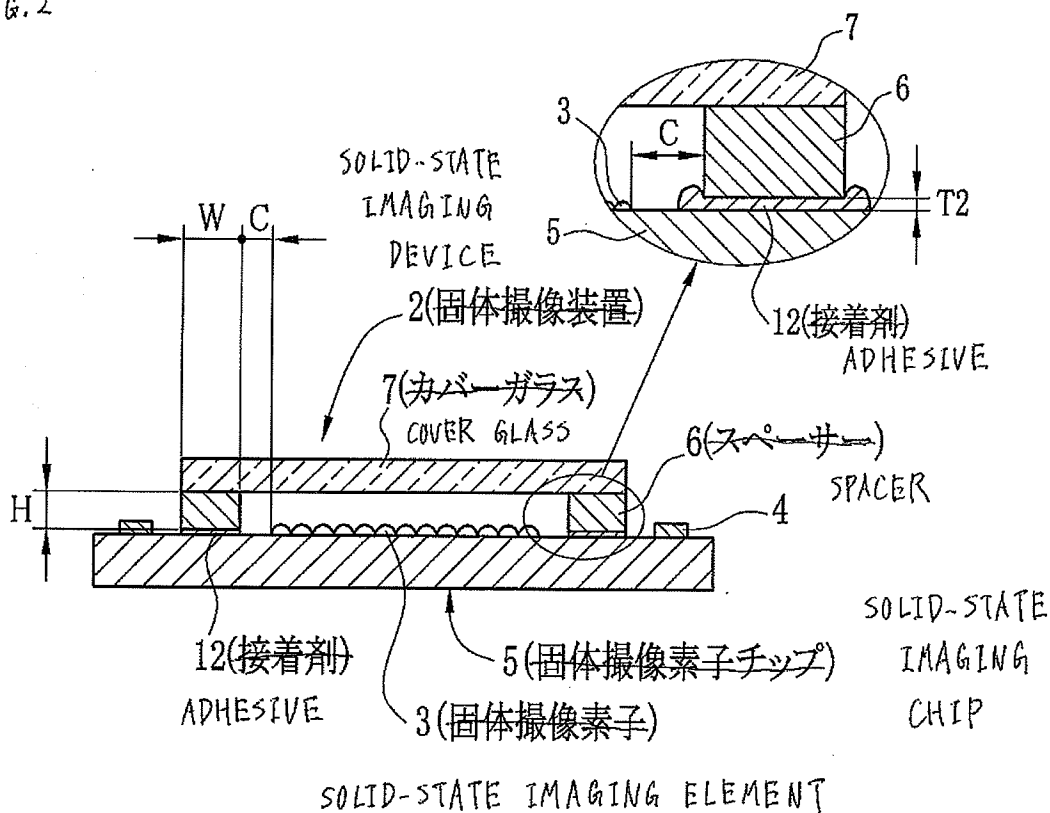
【図1】

FIG.1



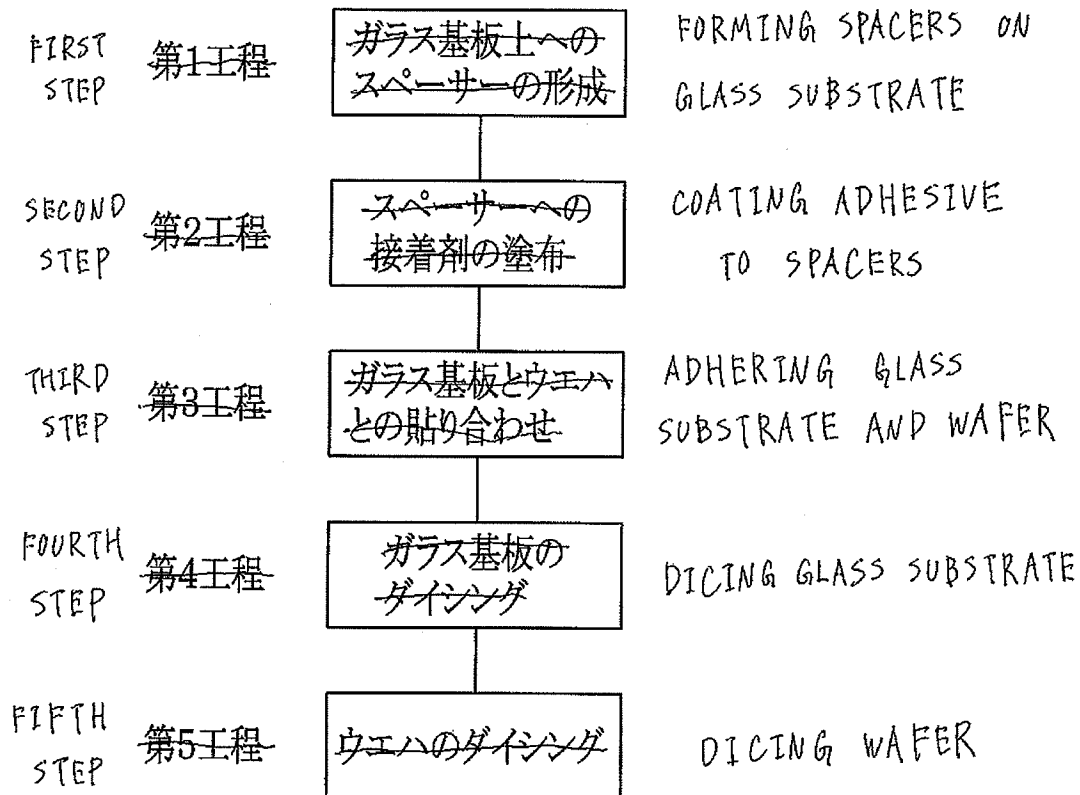
【図2】

FIG.2



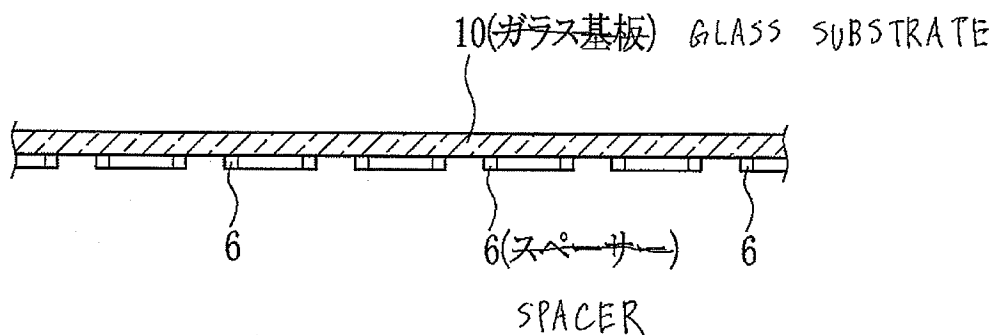
【図3】

FIG.3



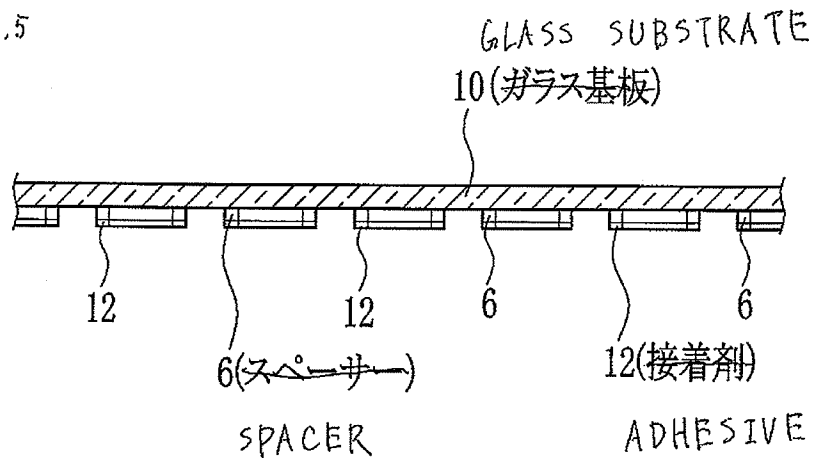
【図4】

FIG.4



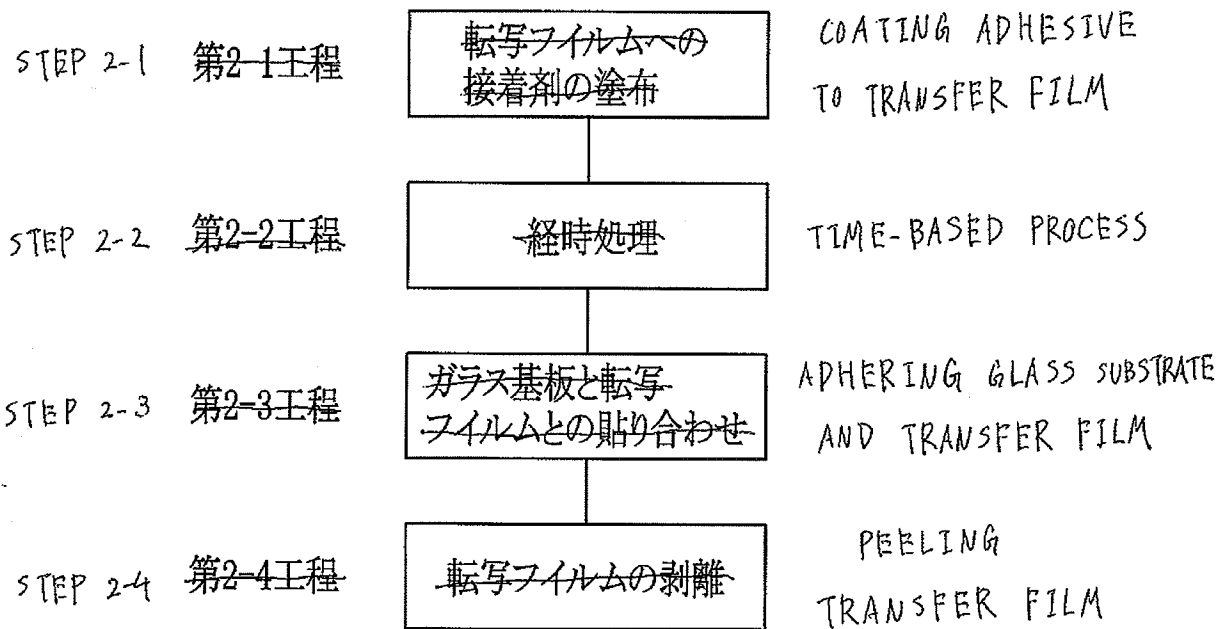
【図5】

FIG.5



【図6】

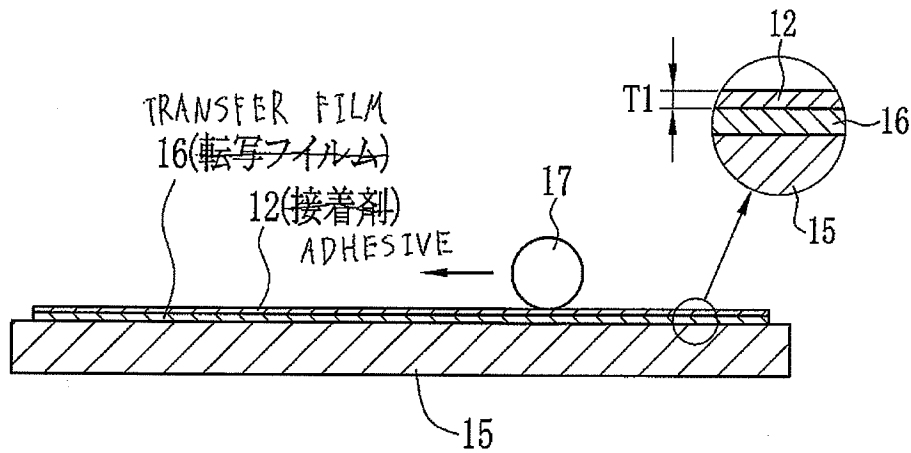
FIG.6



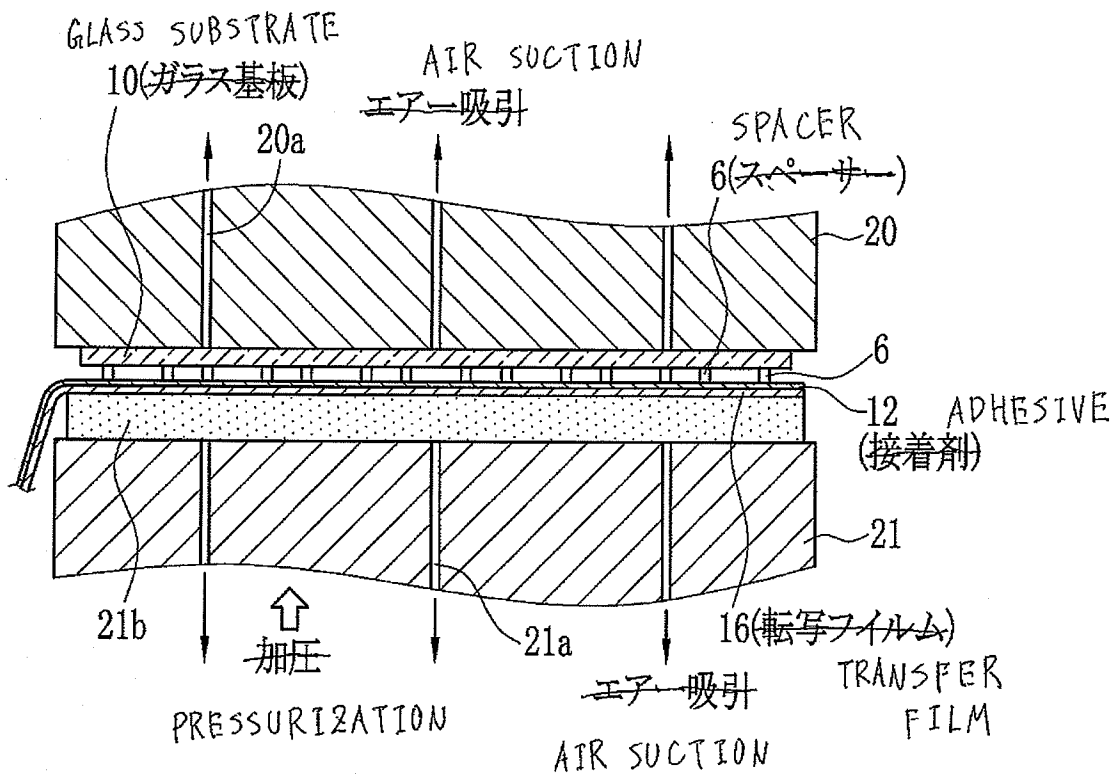
【図7】

FIG. 7

(A)

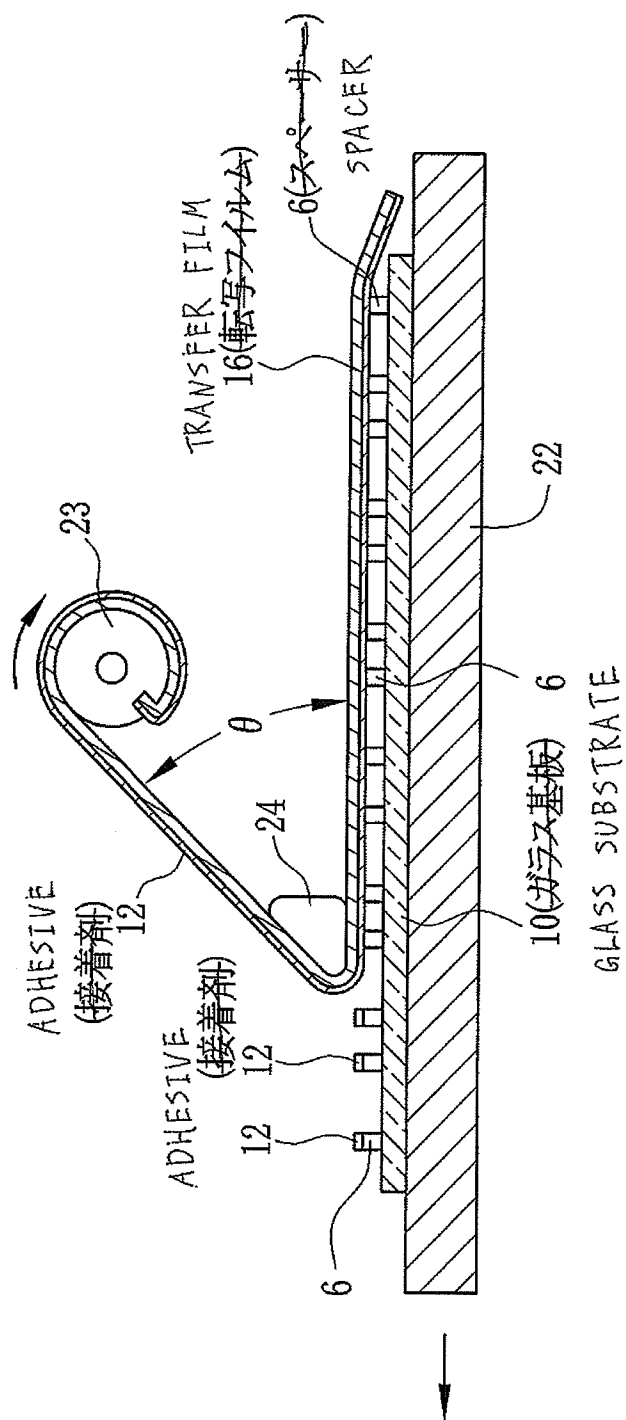


(B)



【図8】

FIG. 8



【图9】

FIG. 9

(A)

WEAK  
PRESSURIZATION  
弱加压

AIR SUCTION  
~~エア吸引~~

GLASS SUBSTRATE  
10(ガラス基板)

弱加压  
↓

202

6

SPACER  
— 卩 —)

29

26  
(ウエハ)

WAFER

12  
(接着剤)

ADHESIVE

28a

工ア一吸引

## AIR SUCTION

3

A

3(固体撮像素子)

SOLID-STATE IMAGING ELEMENT

28

(B)

PRESSURIZATION  
加圧

SPACER  
(~~スぺーサ~~)

SOLID-STATE  
IMAGING  
ELEMENT

GLASS SUBSTRATE  
10(ガラス基板)



/

3(固体撮像素子)<sup>F</sup>

33

-33a

-26  
(ウエハ)

WAFER  
20

—

30a

4

1

3

12

12(接着剤)

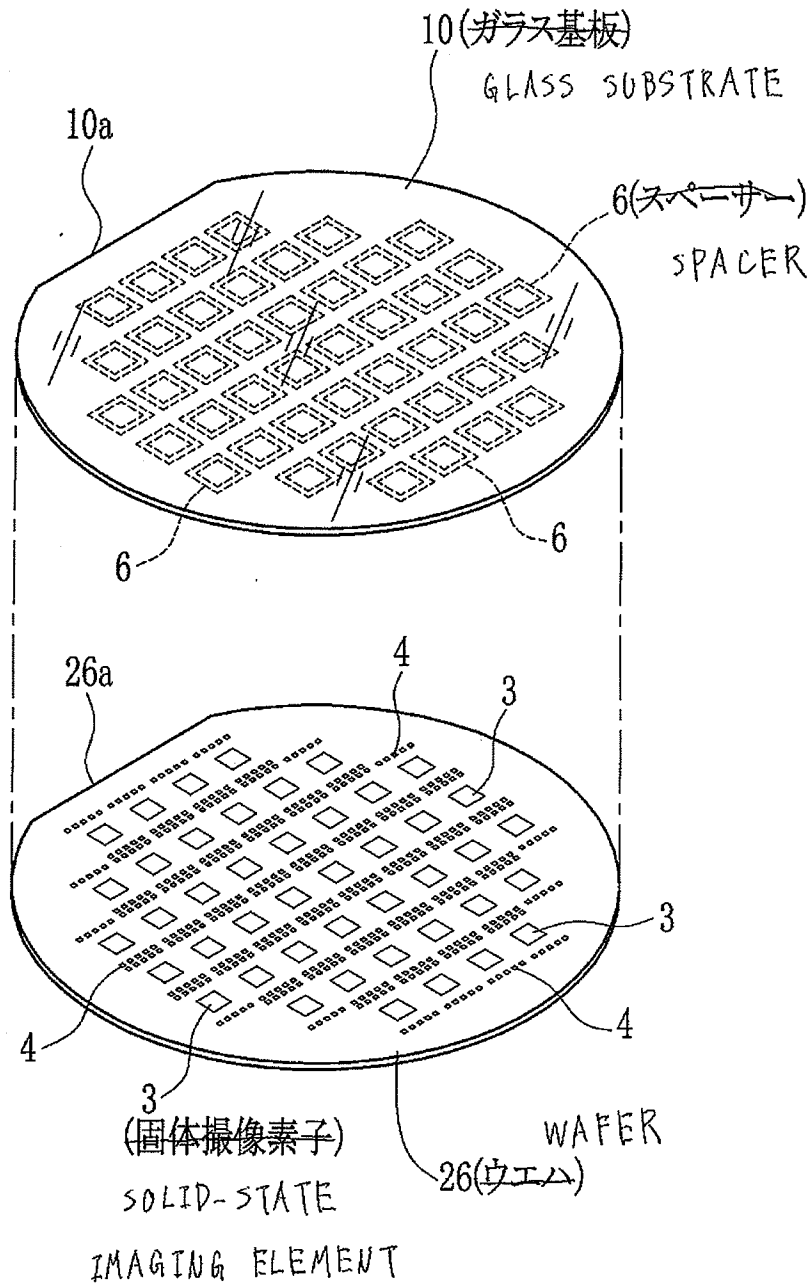
ADHESIVE

~~王子一吸引~~

## AIR SUCTION

【図10】

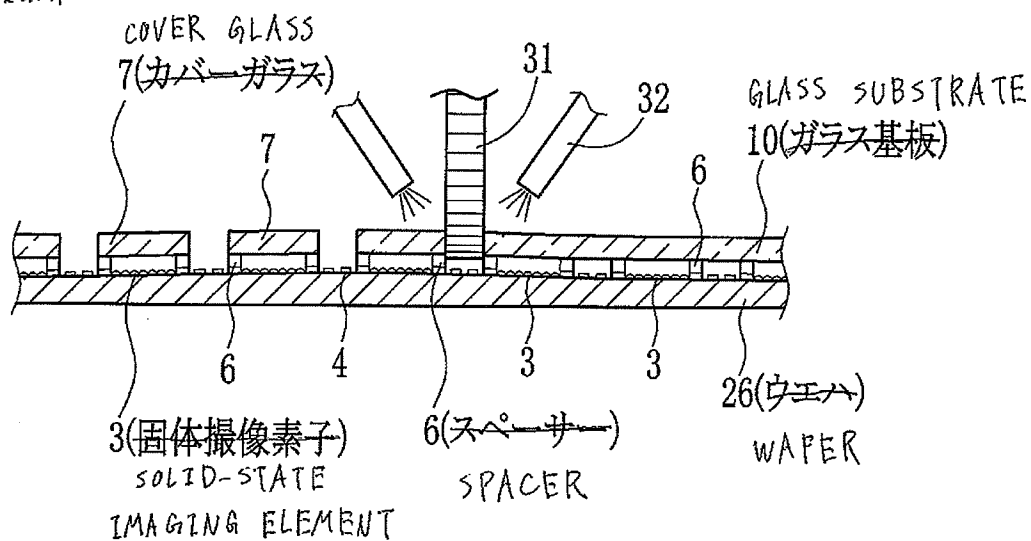
FIG. 10





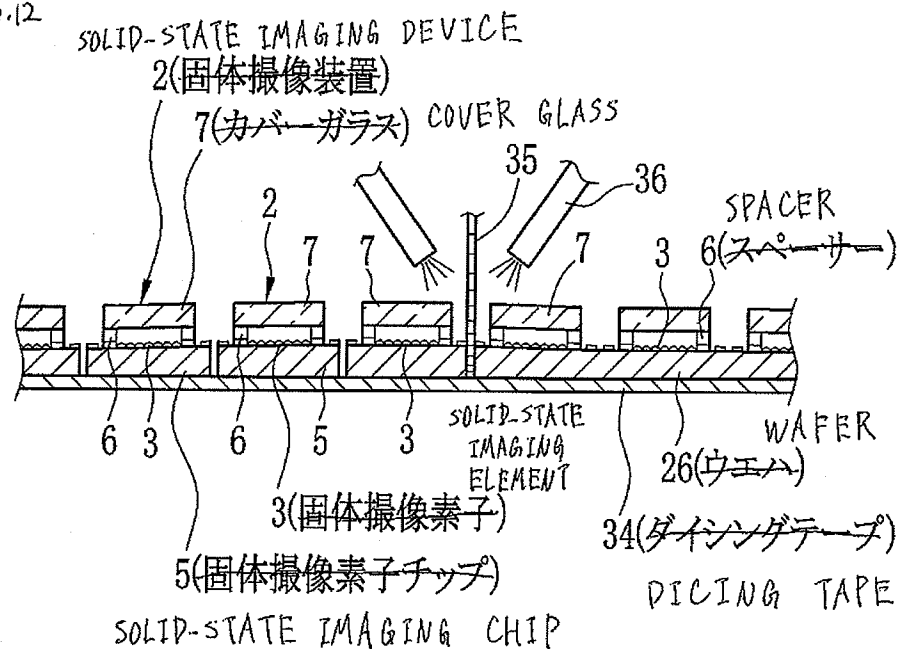
【図1-1】

FIG. 11



【図1-2】

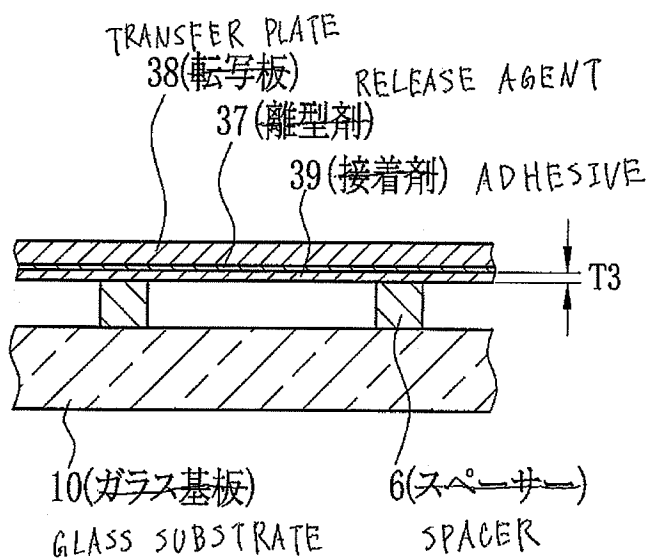
FIG. 12



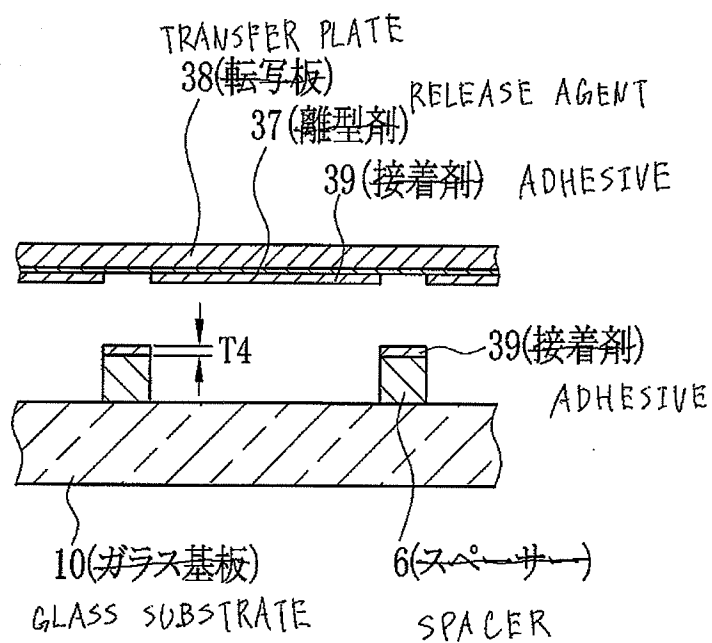
【図13】

FIG. 13

(A)



(B)



【图1-4】

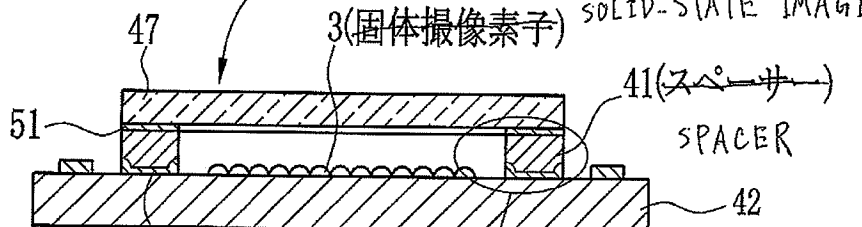
FIG. 14

# SOLID-STATE IMAGING DEVICE

40(固体摄像装置)

### 3(固体撮像素子)

# SOLID-STATE IMAGING ELEMENT



SPACER

CHAMFER

【图1-5】

FIG. 15

FIRST STEP ~~第1ステップ~~

ガラス基板とスペーサ用  
ウエハとの貼り合わせ

## ADHERING GLASS SUBSTRATE AND WAFER FOR SPACER

SECOND STEP ~~第2ステップ~~

## レジストマスクの作成

## FORMING RESIST MASK

THIRD STEP 第3ステップ

面取り部の形成  
(等方性ドライエッチング)

FORMING CHAMFERS  
(ISOTROPIC DRY ETCHING)

FOURTH STEP ~~第4ステップ~~

スぺーサの形成  
(異方性ドライエッチング)

FORMING SPACERS  
(ANISOTROPIC DRY ETCHING)

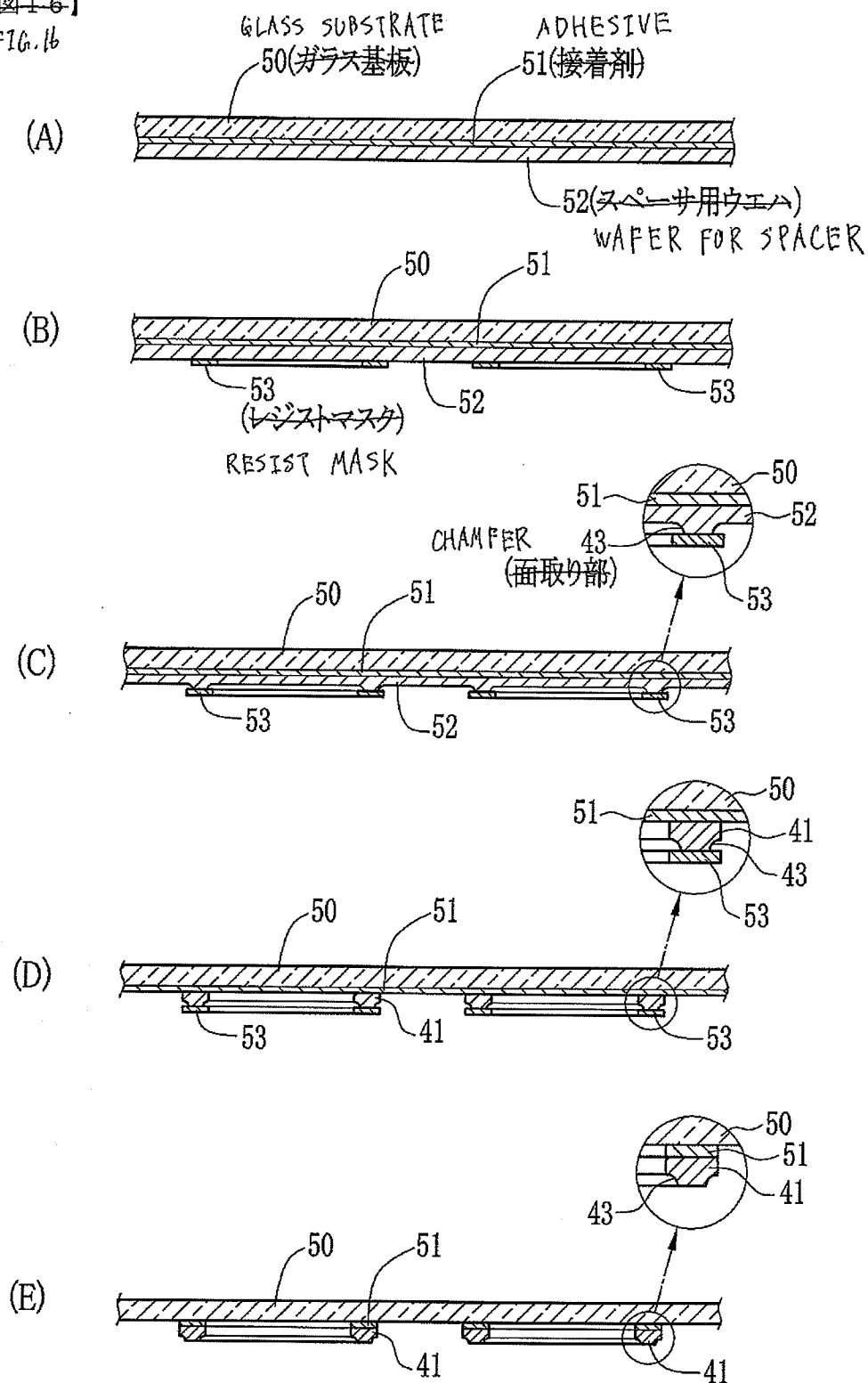
FIFTH STEP ~~第5ステップ~~

~~レジストマスク及び~~  
~~接着剤の除去~~

## REMOVING RESIST MASK AND ADHESIVE

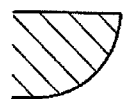
【図16】

FIG. 16



【図17】

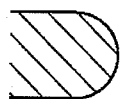
FIG. 17



(F)



(E)



(D)



(C)



(B)



(A)